

### **General Description**

The MAX9384 fully differential dual 2:1 multiplexer (mux) features extremely low propagation delay (560ps max) and output-to-output skew (40ps max). The device is ideal for clock and data multiplexing applications. The two 2:1 muxes are controlled individually or simultaneously through mux select inputs COM\_SEL, SELO, and SEL1. The mux select inputs are compatible with ECL/PECL logic, and are referenced to on-chip outputs V<sub>BB0</sub> and V<sub>BB1</sub>, nominally V<sub>CC</sub> - 1.33V.

The differential inputs D,  $\overline{D}$  can be configured to accept a single-ended signal when the unused complementary input is connected to the on-chip supply output VBB as a reference voltage. All the differential inputs have bias and clamp circuits that force the outputs to a low default when the inputs are left open or at VEE. The single-ended mux select inputs have pulldowns to VEE, providing low default inputs when the select inputs are left open.

The device operates with a wide supply range (VCC -VEE) of +3.0V to +5.5V for PECL or -3.0V to -5.5V for ECL, and is pin compatible with the MC100LVEL56 and MC100EL56. The MAX9384 is offered in a 20-pin wide SO package, and is specified for operation from -40°C to +85°C.

## **Applications**

High-Speed Telecom, Datacom Applications Central-Office Backplane Clock Distribution Access Multiplexers (DSLAM/DLC)

Functional Diagram appears at end of data sheet.

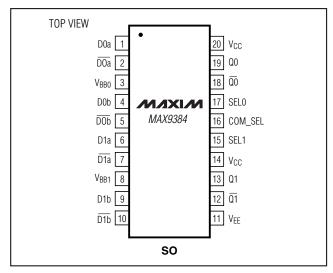
### **Features**

- ♦ 40psp-p Deterministic Jitter
- ♦ 440ps Differential Propagation Delay
- ♦ 12ps Output-to-Output Skew
- ♦ Individual and Common Select
- ♦ +3.0V to +5.5V Supplies for Differential LVPECL/PECL
- ◆ -3.0V to -5.5V Supplies for Differential LVECL/ECL
- ♦ Outputs Low for Inputs Open or at VEE
- ♦ >2kV ESD Protection (Human Body Model)
- ♦ Pin Compatible with MC100LVEL56 and MC100EL56

### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX9384EWP	-40°C to +85°C	20 Wide SO

### Pin Configuration



### **ABSOLUTE MAXIMUM RATINGS**

$V_{CC}$ - $V_{EE}$	
Continuous Output Current	
Surge Output Current	100mA
VBB Sink/Source Current	±0.65mA
Junction-to-Ambient Thermal Resistance in Still Air	
20-Lead Wide SO	+100°C/W
Junction-to-Ambient Thermal Resistance with 500LFPM Airflow	
20-Lead Wide SO	+58°C/W

Junction-to-Case Thermal Resistance
20-Lead Wide SO+20°C/W
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
20-Lead Wide SO
(derate 10mW/°C above +70°C)800mW
Operating Temperature Range40°C to +85°C
Junction Temperature+150°C
Storage Temperature Range65°C to +150°C
ESD Protection
Human Body Model
(D_, D_, Q_, Q_, SEL_, COM_SEL)≥ 2kV
Soldering Temperature (10s)+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} - V_{EE} = 3.0V \text{ to } 5.5V, \text{ outputs loaded with } 50\Omega \pm 1\% \text{ to } V_{CC} - 2V. \text{ Typical values are at } V_{CC} - V_{EE} = 3.3V, V_{IHD} = V_{CC} - 1V, V_{ILD} = V_{CC} - 1.5V, \text{ unless otherwise noted.})$  (Notes 1, 2, 3)

DADAMETED	0.41001	CONDITIONS	-40°C			+25°C			+85°C			шито
PARAMETER	SYMBOL		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
SINGLE-ENDED IN	SINGLE-ENDED INPUT SEL_, COM_SEL											
Input High Voltage	VIH	Internally referenced to V <sub>BB</sub> , Figure 1	V <sub>CC</sub> - 1.165		V <sub>C</sub> C	V <sub>CC</sub> - 1.165		V <sub>C</sub> C	V <sub>CC</sub> - 1.165		V <sub>C</sub> C	V
Input Low Voltage	VIL	Internally referenced to V <sub>BB</sub> , Figure 1	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V
Input Current	I <sub>IN</sub>	V <sub>IH</sub> , V <sub>IL</sub>	-10		+50	-10		+50	-10		+50	μΑ
DIFFERENTIAL INI	PUT (D_, D_	_)										
Single-Ended Input High Voltage	VIH	V <sub>BB</sub> connected to the unused input, Figure 1	V <sub>CC</sub> - 1.165		V <sub>C</sub> C	V <sub>CC</sub> - 1.165		Vcc	V <sub>CC</sub> - 1.165		Vcc	V
Single-Ended Input Low Voltage	VIL	V <sub>BB</sub> connected to the unused input, Figure 1	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V <sub>CC</sub> - 1.810		V <sub>CC</sub> - 1.475	V
High Voltage of Differential Input	VIHD	Figure 1	V <sub>EE</sub> + 1.3		Vcc	V <sub>EE</sub> + 1.2		Vcc	V <sub>EE</sub> + 1.2		Vcc	V
Low Voltage of Differential Input	V <sub>ILD</sub>	Figure 1	VEE		V <sub>CC</sub> - 0.095	VEE		V <sub>CC</sub> - 0.095	VEE		V <sub>CC</sub> - 0.095	V
Differential Input Voltage	V <sub>IHD</sub> - V <sub>ILD</sub>	Figure 1	0.095		3.0	0.095		3.0	0.095		3.0	V
Input Current	I <sub>IN</sub>	V <sub>IH</sub> , V <sub>IL</sub> , V <sub>IHD</sub> , V <sub>ILD</sub>	-100		+100	-100		+100	-100		+100	μΑ

### DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} - V_{EE} = 3.0V \text{ to } 5.5V, \text{ outputs loaded with } 50\Omega \pm 1\% \text{ to } V_{CC} - 2V. \text{ Typical values are at } V_{CC} - V_{EE} = 3.3V, V_{IHD} = V_{CC} - 1V, V_{ILD} = V_{CC} - 1.5V, \text{ unless otherwise noted.})$  (Notes 1, 2, 3)

PARAMETER	SYMBOL	CONDITIONS		-40°C		+25°C			+85°C			UNITS
FARAWEIER STWD		CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
OUTPUT $(Q_{-}, \overline{Q_{-}})$												
Single-Ended Output High Voltage	Voh	Figure 2	V <sub>CC</sub> - 1.085	V <sub>CC</sub> - 0.998	V <sub>CC</sub> - 0.880	V <sub>C</sub> C - 1.025		V <sub>CC</sub> - 0.880	V <sub>CC</sub> - 1.025	V <sub>CC</sub> - 0.929	V <sub>CC</sub> - 0.880	V
Single-Ended Output Low Voltage	V <sub>OL</sub>	Figure 2	V <sub>CC</sub> - 1.830	V <sub>CC</sub> - 1.707	V <sub>CC</sub> - 1.555		V <sub>CC</sub> - 1.685	V <sub>CC</sub> - 1.620	V <sub>CC</sub> - 1.810	V <sub>CC</sub> - 1.690	V <sub>CC</sub> - 1.620	V
Differential Output Voltage	V <sub>OH</sub> - V <sub>OL</sub>	Figure 2	600			640			660			mV
REFERENCE OUT	PUT (V <sub>BB</sub> )											
Reference Voltage Output	V <sub>BB</sub>	I <sub>BB</sub> = ±0.5mA (Note 4)	V <sub>CC</sub> - 1.38	V <sub>CC</sub> - 1.322	V <sub>CC</sub> - 1.26	V <sub>CC</sub> - 1.38	V <sub>CC</sub> - 1.330	V <sub>CC</sub> - 1.26	V <sub>CC</sub> - 1.38	V <sub>CC</sub> - 1.335	V <sub>CC</sub> - 1.26	V
SUPPLY												
Supply Current	IEE	(Note 5)		15	24	_	17	24		19	24	mA

#### **AC ELECTRICAL CHARACTERISTICS**

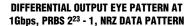
 $(V_{CC} - V_{EE} = 3.0 \text{V to } 5.5 \text{V}, \text{ outputs loaded with } 50\Omega \pm 1\% \text{ to } V_{CC} - 2 \text{V}, V_{IHD} - V_{ILD} = 0.15 \text{V to } 1 \text{V}, f_{IN} \le 500 \text{MHz}, \text{ input duty cycle} = 50\%, input transition time = 125ps (20% to 80%). Typical values are at <math>V_{CC} - V_{EE} = 3.3 \text{V}, V_{IHD} = V_{CC} - 1 \text{V}, V_{ILD} = V_{CC} - 1.5 \text{V}, \text{ unless otherwise noted.})$  (Note 6)

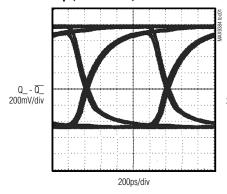
DADAMETED	SYMBOL	CONDITIONS		-40°C		+25°C			+85°C			UNITS
PARAMETER	SYMBOL		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Differential Input-to-Output Delay	t <sub>PLHD</sub> , t <sub>PHLD</sub>	Figure 2	340		540	350		550	360		560	ps
Single-Ended Input-to-Output Delay	tPLH1, tPHL1	Figure 3 (Note 7)	290		540	310		560	330		580	ps
SEL_ and COM_SEL to Output Delay	tPLH2, tPHL2	Figure 4 (Note 7)	310		730	320		740	330		750	ps
Output-to-Output Skew	tskoo	(Note 8)		12	40		12	40		12	40	ps
Added Random Jitter	t <sub>RJ</sub>	f <sub>IN</sub> = 500MHz (Note 9)		0.3	0.8		0.4	0.8		0.5	0.8	ps <sub>(RMS)</sub>
Added Deterministic Jitter	t <sub>D</sub> J	1.0Gbps 2 <sup>23</sup> - 1 PRBS pattern (Note 9)		40	70		40	70		40	70	ps(P-P)
Switching Frequency	fMAX	V <sub>OH</sub> - V <sub>OL</sub> ≥ 300mV, Figure 2	1.5			1.5			1.5			GHz
Output Rise and Fall Time (20% to 80%)	t <sub>R</sub> , t <sub>F</sub>	Figure 2	200	310	440	200	310	440	200	310	440	ps

- **Note 1:** Measurements are made with the device in thermal equilibrium.
- Note 2: Current into a pin is defined as positive. Current out of a pin is defined as negative.
- **Note 3:** DC parameters production tested at  $T_A = +25^{\circ}C$  and guaranteed by design over the full operating temperature range.
- Note 4: Use VBB only for inputs that are on the same device as the VBB reference.
- Note 5: All pins open except  $V_{CC}$  and  $V_{EE}$ .
- Note 6: Guaranteed by design and characterization. Limits are set at ±6 sigma.
- **Note 7:** Test conditions are  $V_{IH} = V_{CC} 1.11V$  and  $V_{IL} = V_{CC} 1.53V$ .
- Note 8: Measured between outputs of the same part at the signal crossing points for a same-edge transition. Differential input signal.
- Note 9: Device jitter added to the input signal. Differential input signal.

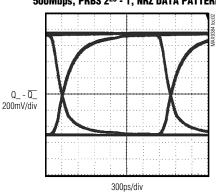
## **Typical Operating Characteristics**

 $(V_{CC} - V_{EE} = 3.3V, V_{IHD} = V_{CC} - 1V, V_{ILD} = V_{CC} - 1.5V, COM_SEL = low, SEL_ = low, outputs loaded with 50<math>\Omega$  ±1% to  $V_{CC} - 2V$ ,  $f_{IN} = 500MHz$ , input duty cycle = 50%, input transition time = 125ps (20% to 80%), unless otherwise noted.)

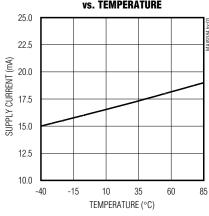




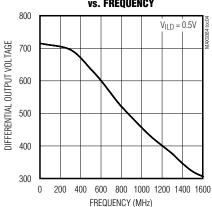
## DIFFERENTIAL OUTPUT EYE PATTERN AT 500Mbps, PRBS 2<sup>23</sup> - 1, NRZ DATA PATTERN



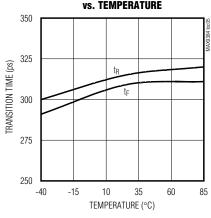
#### SUPPLY CURRENT (I<sub>EE</sub>) vs. temperature



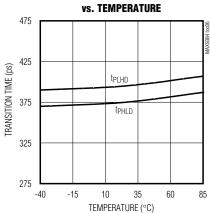
#### OUTPUT AMPLITUDE (V<sub>OH</sub> - V<sub>OL</sub>) vs. Frequency



## TRANSITION TIME vs. TEMPERATURE



## DIFFERENTIAL PROPAGATION DELAY vs. Temperature



## **Pin Description**

PIN	NAME	FUNCTION
1	D0a	Noninverting Differential Input ${f a}$ for MUX 0. Internal 120k $\Omega$ pulldown to V <sub>EE</sub> .
2	D0a	Inverting Differential Input <b>a</b> for MUX 0. Internal $120k\Omega$ pulldown to $V_{EE}$ and $120k\Omega$ pullup to $V_{CC}$ .
3	V <sub>BB0</sub>	Reference Output Voltage. Connect to the inverting or noninverting clock input to provide a reference for single-ended operation. When used, bypass VBB0 to VCC with a 0.01µF ceramic capacitor. Otherwise leave open. VBB0 is internally connected to VBB1.
4	D0b	Noninverting Differential Input <b>b</b> for MUX 0. Internal 120kΩ pulldown to V <sub>EE</sub> .
5	D0b	Inverting Differential Input $\bf b$ for MUX 0. Internal 120k $\Omega$ pulldown to $V_{EE}$ and 120k $\Omega$ pullup to $V_{CC}$ .
6	D1a	Noninverting Differential Input <b>a</b> for MUX 1. Internal 120kΩ pulldown to V <sub>EE</sub> .
7	D1a	Inverting Differential Input <b>a</b> for MUX 1. Internal $120k\Omega$ pulldown to $V_{EE}$ and $120k\Omega$ pullup to $V_{CC}$ .
8	V <sub>BB1</sub>	Reference Output Voltage. Connect to the inverting or noninverting clock input to provide a reference for single-ended operation. When used, bypass V <sub>BB1</sub> to V <sub>CC</sub> with a 0.01µF ceramic capacitor. Otherwise leave open. V <sub>BB1</sub> is internally connected to V <sub>BB0</sub> .
9	D1b	Noninverting Differential Input <b>b</b> for MUX 1. Internal 120kΩ pulldown to V <sub>EE</sub> .
10	D1b	Inverting Differential Input <b>b</b> for MUX 1. Internal $120k\Omega$ pulldown to $V_{EE}$ and $120k\Omega$ pullup to $V_{CC}$ .
11	VEE	Negative Supply Voltage
12	Q1	Inverting Output for MUX 1. Typically terminate with $50\Omega$ resistor to $V_{CC}$ - $2V$ .
13	Q1	Noninverting Output for MUX 1. Typically terminate with $50\Omega$ resistor to $V_{CC}$ - 2V.
14, 20	Vcc	Positive Supply Voltage. Bypass each V <sub>CC</sub> to V <sub>EE</sub> with 0.1µF and 0.01µF ceramic capacitors. Place the capacitors as close to the device as possible with the smaller value capacitor closest to the device.
15	SEL1	Select Logic Input for MUX 1. Internal 210kΩ pulldown to VEE.
16	COM_SEL	Common Select Logic Input. Internal 210kΩ pulldown to VEE.
17	SEL0	Select Logic Input for MUX 0. Internal 210kΩ pulldown to VEE.
18	Q0	Inverting Output for MUX 0. Typically terminate with $50\Omega$ resistor to $V_{CC}$ - $2V$ .
19	Q0	Noninverting Output for MUX 0. Typically terminate with $50\Omega$ resistor to $V_{CC}$ - 2V.

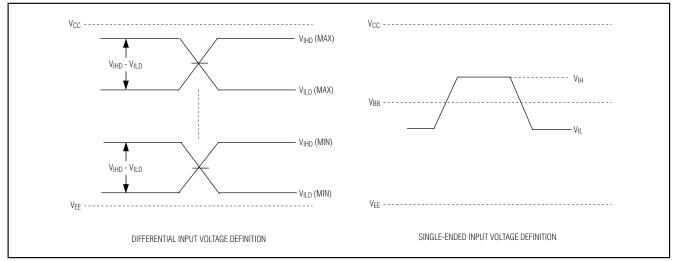


Figure 1. Input Definitions

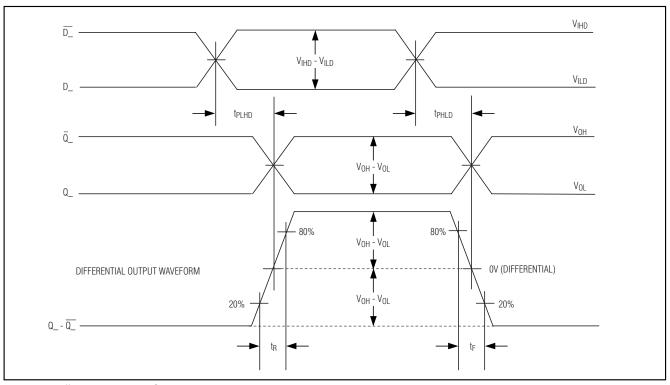


Figure 2. Differential Input-to-Output Propagation Delay Timing Diagram

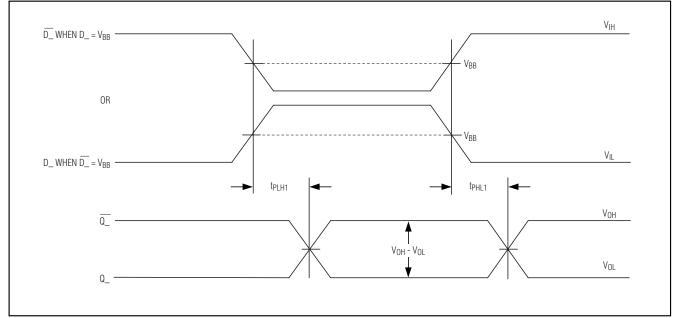


Figure 3. Single-Ended Input-to-Output Propagation Delay Timing Delay

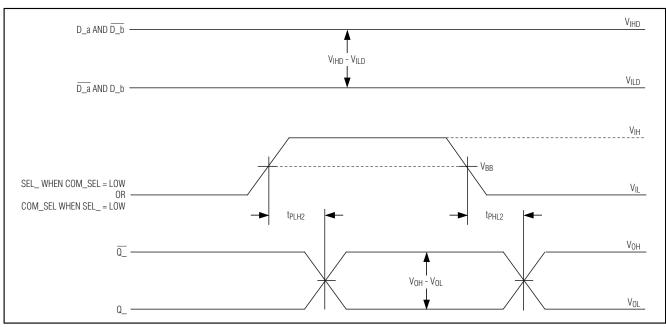


Figure 4. Select Inputs (COM\_SEL, SEL\_) to Output (Q\_,  $\overline{Q}$ ) Delay Timing Diagram

### **Detailed Description**

The MAX9384 dual differential 2:1 multiplexer features extremely low propagation delay (560ps max) and output-to-output skew (40ps max). These features make the device ideal for clock and data multiplexing applications.

The two differential muxes are controlled individually or simultaneously through select control inputs, SEL0, SEL1, and COM\_SEL (see Table 1). The select control inputs are referenced to VBB (nominally VCC - 1.33V) and are internally pulled down to VEE through 210k $\Omega$  resistors. By default, the select inputs are low when left open.

The differential inputs D\_,  $\overline{\rm D}_{\rm L}$  can be configured to accept a single-ended signal when the unused complementary input is connected to the on-chip reference voltage VBB. The reference output voltage, pins VBB0 and VBB1, provides the input reference voltage for single-ended operation for each mux. A single-ended input of at least VBB\_  $\pm 95$ mV or a differential input of at least 95mV switches the outputs to the VOH and VOL levels

**Table 1. Input Select Truth Table** 

CONTR	DATA INPUT	
COM_SEL	SEL_	$D_{\!-},\overline{D}_{\!-}$
Loropon	L or open	b <sup>*</sup>
L or open	Н	а
Н	X	a

<sup>\*</sup>Default input when COM\_SEL and SEL\_ are left open.

specified in the *DC Electrical Characteristics*. The maximum magnitude of the differential input from D\_ to  $\overline{D}$ \_ is  $\pm 3.0 \text{V}$ . Specifications for the high and low voltages of a differential input (VIHD and VILD) and the differential input voltage (VIHD - VILD) apply simultaneously.

The device operates over a wide supply range ( $V_{CC}$  -  $V_{EE}$ ) of +3.0V to +5.5V for PECL or -3.0V to -5.5V for ECL, and is pin compatible with the MC100LVEL56 and MC100EL56.

#### Single-Ended Operation

A single-ended input can be driven to VCC and VEE or by a single-ended LVPECL/LVECL signal. D\_,  $\overline{\rm D}_{-}$  are differential inputs but can be configured to accept single-ended inputs. This is accomplished by connecting the on-chip reference voltage, VBB\_, to an unused complementary input as a reference. For example, the differential D0a,  $\overline{\rm D0a}$  input is converted to a noninverting, single-ended input by connecting VBB0 to  $\overline{\rm D0a}$  and connecting the single-ended input to D0a. Similarly, an inverting input is obtained by connecting VBB0 to D0a and connecting the single-ended input to  $\overline{\rm D0a}$ .

When using the V<sub>BB</sub>\_ reference output, bypass it with a 0.01 $\mu$ F ceramic capacitor to V<sub>CC</sub>. If not used, leave it open. The V<sub>BB</sub>\_ reference can source or sink 0.5mA, which is sufficient to drive two inputs.

### **Applications Information**

#### **Output Termination**

Terminate the outputs through  $50\Omega$  to VCC - 2V or use equivalent Thevenin terminations. Terminate each Q\_ and  $\overline{\rm Q}_-$  output with identical termination on each for minimal distortion. When a single-ended signal is taken from the differential output, terminate both Q\_ and  $\overline{\rm Q}_-$ . Ensure that output currents do not exceed the current limits as specified in the *Absolute Maximum Ratings* table. Under all operating conditions, the device's total thermal limits should be observed.

#### **Supply Bypassing**

Bypass each VCC to VEE with high-frequency surface-mount ceramic  $0.1\mu F$  and  $0.01\mu F$  capacitors. Place the capacitors as close to the device as possible, with the  $0.01\mu F$  capacitor closest to the device pins.

Use multiple vias when connecting the bypass capacitors to ground. When using the  $V_{BB0}$  or  $V_{BB1}$  reference outputs, bypass each one with a  $0.01\mu F$  ceramic capacitor to  $V_{CC}.$  If the  $V_{BB0}$  or  $V_{BB1}$  reference outputs are not used, they can be left open.

#### Traces

Circuit board trace layout is very important to maintain the signal integrity of high-speed differential signals. Maintaining integrity is accomplished in part by reducing signal reflections and skew, and increasing common-mode noise immunity.

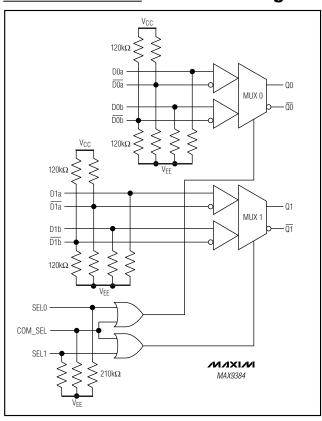
Signal reflections are caused by discontinuities in the  $50\Omega$  characteristic impedance of the traces. Avoid discontinuities by maintaining the distance between differential traces, not using sharp corners or using vias. Maintaining distance between the traces also increases common-mode noise immunity. Reducing signal skew is accomplished by matching the electrical length of the differential traces.

### **Chip Information**

TRANSISTOR COUNT: 485

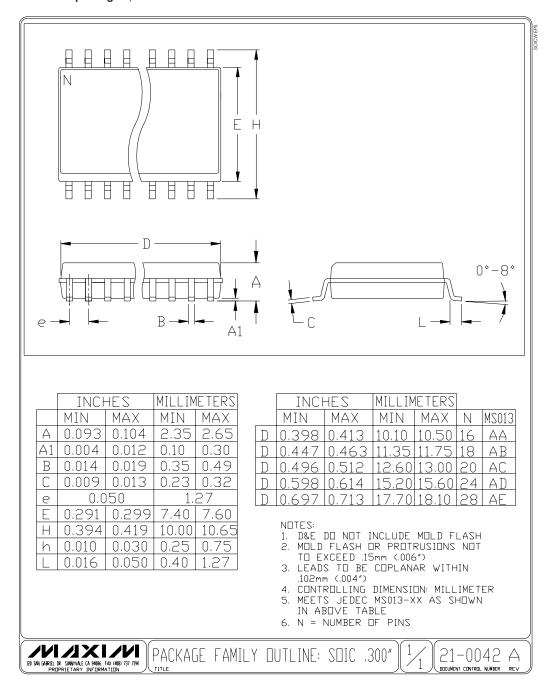
PROCESS: Bipolar

### **Functional Diagram**



### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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